Please amend the subject application as follows:

IN THE SPECIFICATION:

Illustrated in FIG. 3 is a wafer 50 illustrating one form of the visual indicator taught herein wherein each die contains a visual indicator. The wafer 50 has a plurality of die, such as die 52. In modern semiconductor processing, the number of die per wafer may be in the thousands. Therefore, the small number of die illustrated in FIG. 3 is for convenience of illustration only. Each die has a visual indicator contained thereon. However, only a portion of the die ~~are~~ is functional and thus only a portion of the visual indicators, such as visual indicator 54, ~~are~~ is operating as illustrated in FIG. 3. The wafer has a plurality of vertical streets, such as street 56, and a plurality of horizontal streets, such as street 58. Contained with the streets, such as street 56 and street 58, is the power supply bus as will be detailed below in connection with FIG. 4. The visual indicators of wafer 50 are present for an LED implementation only as long as the wafer's power distribution system is receiving power. Therefore, a computerized recording is made of the position of each of the active die. Once the power is removed from die 52 pursuant to step 25 of FIG. 1, the visual indicators are also removed. In some embodiments, a permanent, one-time visual indicator that is not removed with the removal of power may be utilized.